REMARKS

This is in response to the Office Action dated May 4, 2005. New dependent claim 17 has been added (e.g., for example support for new claim 17 see resin bin 12b in Fig. 2C, and pg. 27, lines 21-23). Claims 1, 5, 14 and 16-17 are now pending.

Claims 1, 5, 14 and 16 stand rejected under 35 U.S.C. Section 112 and 35 U.S.C. Section 101. While applicant does not agree with these rejections, it is believed that these rejections have been addressed by claim changes herein and have been rendered moot.

Claim 1 stands rejected under 35 U.S.C. Section 102(b) as being allegedly anticipated by Pellerin. This Section 102(b) rejection is respectfully traversed for at least the following reasons.

Claim 1 as amended requires "at least an upper die and a lower die provided with a cavity into which a liquid resin is injected to form the resin upon curing; a resin inlet provided within the upper die to inject the liquid resin into the cavity; and an air vent that serves as a passage for the liquid resin and through which air within the cavity and the resin inlet can be released to an exterior space of the resin molding die." Thus, at least one air vent is provided, which air vent is used for releasing air to an exterior space of the die. For example and without limitation, air vent 12 in figures of the instant application. An example advantage of the air vent serving as a passage for liquid resin is that the injected resin may flow, at a pressure which is in the neighborhood of a pressure imposed by its own weight, from the cavity into the air vent thereby allowing injecting a resin into the molding die via low-pressure injection (e.g., pg. 16, lines 13-23). The cited art fails to disclose or suggest the aforesaid underlined feature of claim 1.

Pellerin discloses a technique for encapsulating a semiconductor device by resin injection into a molding cavity 20 overlying the device. Pellerin discloses a porous wall 33 through which air can be evacuated, but this wall 33 is impermeable to the resin (col. 3, lines 3-8). Thus,

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Pellerin fails to disclose or suggest an air vent that serves as a passage for liquid resin, and

through which air can be released, as required by claim 1. Pellerin teaches the opposite of what

claim 1 requires in this respect.

Claim 17 requires that the air vent further comprises a resin bin. For example and

without limitation, Fig. 2C of the instant application illustrates that the air vent further includes

resin bin 12b. Pellerin fails to disclose or suggest the resin bin required by new claim 17.

It is respectfully requested that all rejections be withdrawn. All claims are in condition

for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone

the undersigned with regard to the same.

Respectfully submitted,

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